COLLMER.COM
Power Electronics Specialists
(formerly Collmer Semiconductor, Inc.)

T2SBA Series (SIP)

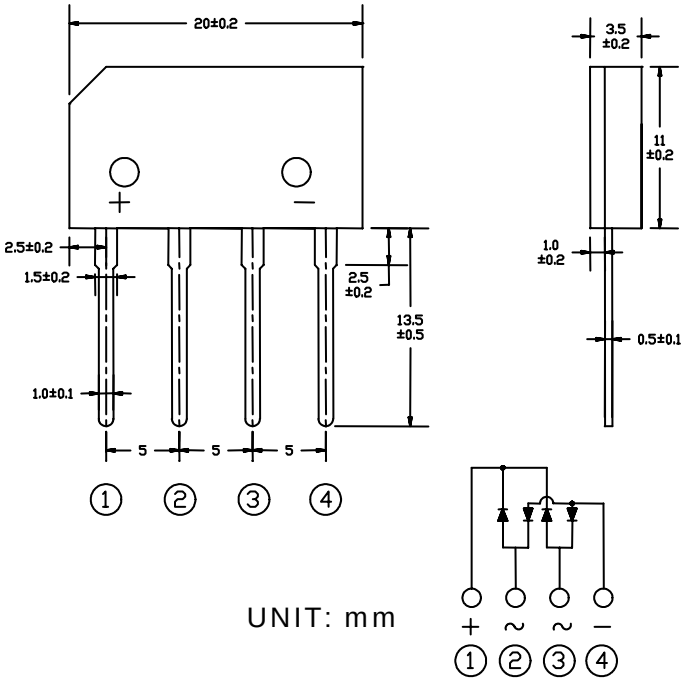
1.5-AMPERE SILICON BRIDGE RECTIFIER

FEATURES

- Low Reverse Leakage Current
- Surge Overload Rating to 60A Peak
- Ideal for Printed Circuit Board Applications
- Epoxy Material – UL Recognition Flammability Classification 94V-0

Mechanical Data

- Case: Molded Epoxy Resin
- Terminals: Plated Leads, Solderable per MIL-STD-202, Method 208
- Polarity: Molded on Body



UNIT: mm

Maximum Ratings & Characteristics

Single Phase, 60 Hz, Resistive or Inductive Load
T_a = 25ºC Unless Otherwise Specified

CHARACTERISTIC	SYMBOL	T2SBA40	T2SBA60	T2SBA80	UNIT
Peak Repetitive Reverse Voltage	V_{RRM}	400	600	800	V
RMS Reverse Voltage	$V_{R(RMS)}$	280	420	560	V
Average Rectified Output Current @ T_a = 25ºC	I_o	1.5			A
Non-Repetitive Peak Forward Surge Current 10 mS single half sine-wave superimposed on rated load	I_{FSM}	60			A
Maximum Forward Voltage per Element, I_F = 0.75 A	V_F	1.05			V
Peak Reverse Current per element at $V_R = V_{RRM}$	I_R	10			µA
Operating and Storage Temperature Range	T_J ,T_{stg}	-40 to +150			°C

Manufactured by Tianjin Zhong – Huan Semiconductor Co., Ltd.

Rev 0, Sep 2002

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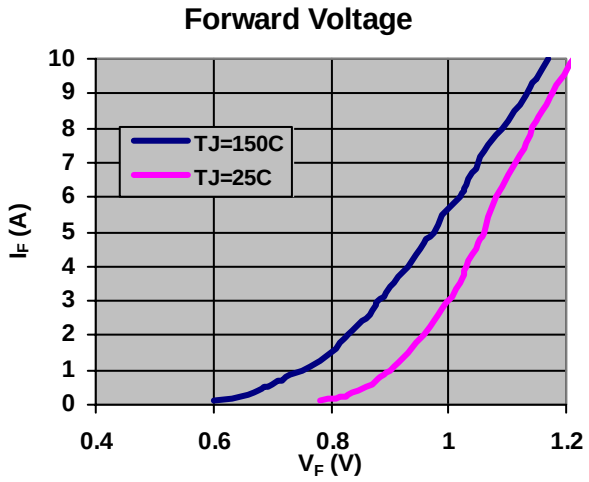

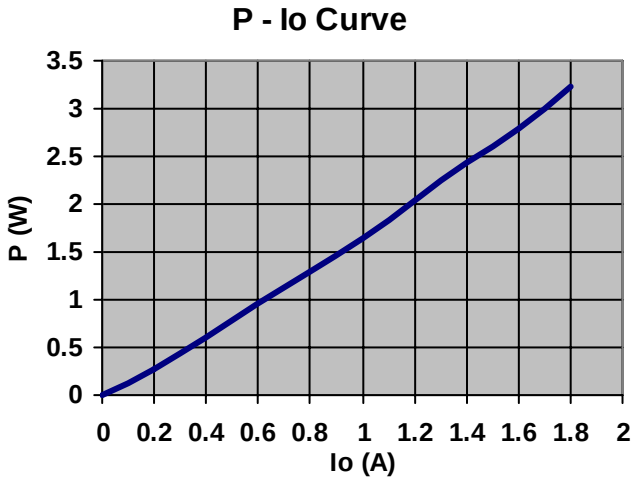

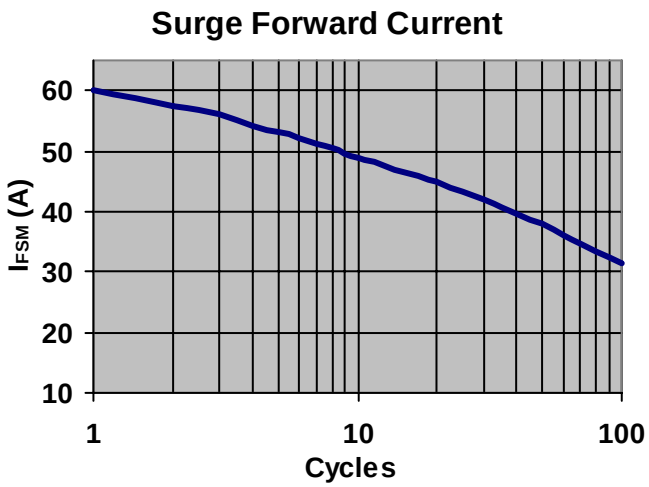

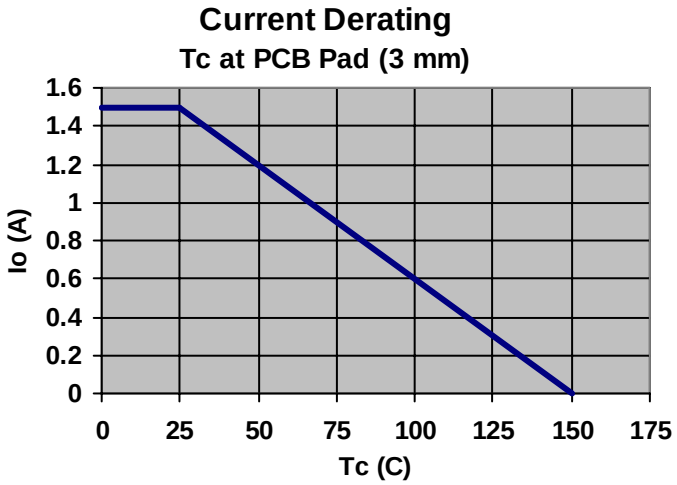

In order to avoid damaging devices, please observe the following precautions:

1. When using automated soldering equipment, use 60/40 (Sn/Pb) solder (melting point of 180ºC) with a neutral flux similar to rosin. Preheat time should be limited to 1 – 2 minutes at 150ºC.
2. When using a soldering iron, use a tip temperature of less than 300ºC (or a soldering iron power of less than 60W). Keep the soldering time below 5 seconds.
3. After soldering, remove any flux residue to avoid corrosion.
4. Because over-voltage or over-current testing may cause permanent damage to the devices, be sure to check the test equipment for proper voltage, current and ground connection prior to beginning the test.
5. If the devices are to be encapsulated, they should be cleaned and dried at 120º ± 5ºC for at least 24 hours prior to encapsulation. Test for compatibility between the device package and the encapsulation material.